

Sample &

🖥 Buy





TL331

SLVS238G - AUGUST 1999 - REVISED JANUARY 2015

TL331 Single Differential Comparator

Technical

Documents

1 Features

- Single Supply or Dual Supplies
- Wide Range of Supply Voltage, 2 V to 36 V
- Low Supply-Current Drain Independent of Supply Voltage, 0.4 mA Typ
- Low Input Bias Current, 25 nA Typ
- Low Input Offset Voltage, 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage, ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS •

Applications 2

- Hysteresis Comparators
- Oscillators
- Window Comparators
- Industrial Equipment
- Test and Measurement

Simplified Schematic 4

3 Description

Tools &

Software

This device consists of a single voltage comparator that is designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible if the difference between the two supplies is 2 V to 36 V and V_{CC} is at least 1.5 V more positive than the input commonmode voltage. Current drain is independent of the supply voltage. The output can be connected to other open-collector outputs to achieve wired-AND relationships.

Device Information⁽¹⁾

PART NUMBER	PACKAGE (PIN)	BODY SIZE (NOM)	
TL331	SOT (5)	2.90 mm × 1.60 mm	

(1) For all available packages, see the orderable addendum at the end of the datasheet.





2

Copyright © 1999–2015, Texas Instruments Incorporated

Table of Contents

1		ures					
2	Applications 1						
3	Des	cription 1					
4	Sim	plified Schematic 1					
5	Revi	ision History 2					
6	Pin	Configuration and Functions 3					
7	Spe	cifications 4					
	7.1	Absolute Maximum Ratings 4					
	7.2	ESD Ratings 4					
	7.3	Recommended Operating Conditions 4					
	7.4	Thermal Information 4					
	7.5	Electrical Characteristics 5					
	7.6	Switching Characteristics 5					
	7.7	Typical Characteristics					
8	Deta	ailed Description 7					
	8.1	Overview					

	8.2	Functional Block Diagram	7
	8.3	Feature Description	7
	8.4	Device Functional Modes	7
9	Appl	lication and Implementation	8
	9.1	Application Information	8
	9.2	Typical Application	8
10	Pow	er Supply Recommendations	. 10
11	Layo	out	10
	11.1	Layout Guidelines	. 10
	11.2	Layout Example	. 10
12	Devi	ice and Documentation Support	. 11
	12.1	Trademarks	. 11
	12.2	Electrostatic Discharge Caution	. 11
	12.3	Glossary	. 11
13		hanical, Packaging, and Orderable mation	. 11

5 Revision History

Changes from Revision F (July 2008) to Revision G

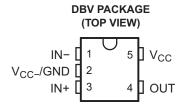
•	Added Applications, Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table, Typical Characteristics, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and	
	Mechanical, Packaging, and Orderable Information section.	1
•	Deleted Ordering Information table.	1
•	Deleted 25°C Specifications in <i>Electrical Characteristics</i> table	5
•	Changed test condition V _{ID} for parameter I _{OL} from 1 V to -1 V in <i>Electrical Characteristics</i> table	5

www.ti.com

Page



6 Pin Configuration and Functions



Pin Functions

Р	IN	TYPE	DESCRIPTION
NAME	NO.	ITFE	DESCRIPTION
IN+	3	Ι	Positive Input
IN-	1	Ι	Negative Input
OUT	4	0	Open Collector/Drain Output
V _{CC}	5	I	Power Supply Input
GND	2	Ι	Ground

Texas Instruments

www.ti.com

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage ⁽²⁾	0	36	V
V_{ID}	Differential input voltage ⁽³⁾	-36	36	V
VI	Input voltage range (either input)	-0.3	36	V
Vo	Output voltage	0	36	V
I _O	Output current	0	20	mA
	Duration of output short-circuit to ground ⁽⁴⁾		Unlimited	
TJ	Operating virtual junction temperature	-40	150	°C
T _{stg}	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to the network ground.

(3) Differential voltages are at IN+ with respect to IN-.

(4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

7.2 ESD Ratings

			VALUE	UNIT
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±1000	
V _(ESD)	Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101, all $\ensuremath{\text{pins}}^{(2)}$	±750	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2	36	V
TJ	Junction Temperature	-40	125	°C

7.4 Thermal Information

	THERMAL METRIC ⁽¹⁾	DBV	UNIT
		5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	218.3	
R _{0JC(top)}	Junction-to-case (top) thermal resistance	87.3	
$R_{\theta JB}$	Junction-to-board thermal resistance	44.9	°C/W
ΨJT	Junction-to-top characterization parameter	4.3	
Ψ_{JB}	Junction-to-board characterization parameter	44.1	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

7.5 Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS ⁽¹⁾	T _A ⁽²⁾	MIN	TYP	MAX	UNIT
V	Input offect veltere	$V_{CC} = 5 V \text{ to } 30 V, V_{O} = 1.4 V,$	25°C		2	5	
V _{IO}	Input offset voltage	$V_{IC} = V_{IC(min)}$	Full range			9	mV
	Input offect ourrest		25°C		5	50	
I _{IO}	Input offset current	$V_0 = 1.4 V$	Full range			250	nA
	Input biog ourrest	$V_{O} = 1.4 V$	25°C		-25	-250	~ ^
I _{IB} Input bias current	input bias current		Full range			-400	nA
V _{ICR}	Common-mode input voltage range ⁽³⁾		Full range	0 to V _{CC} – 1.5			V
A_{VD}	Large-signal differential voltage amplification	$\label{eq:V_CC} \begin{array}{l} V_{CC} = 15 \ V, \ V_O = 1.4 \ V \ to \ 11.4 \ V, \\ R_L \geq 15 \ k\Omega \ to \ V_{CC} \end{array}$	25°C	50	200		V/mV
	High lovel output ourrent	$V_{OH} = 5 \text{ V}, \text{ V}_{ID} = 1 \text{ V}$	25°C		0.1	50	nA
I _{OH}	High-level output current	$V_{OH} = 30 \text{ V}, \text{ V}_{ID} = 1 \text{ V}$	Full range			1	μA
V		$I_{OL} = 4 \text{ mA}, V_{ID} = -1 \text{ V}$	25°C		150	400	mV
V _{OL}	Low-level output voltage		Full range			700	
I _{OL}	Low-level output current	$V_{OL} = 1.5 \text{ V}, V_{ID} = -1 \text{ V}$	25°C	6			mA
I _{CC}	Supply current	$R_L = \infty, V_{CC} = 5 V$	25°C		0.4	0.7	mA

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(2) Full range T_A is -40°C to 85°C for I-suffix devices and -40°C to 105°C for K-suffix devices.

(3) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V without damage.

7.6 Switching Characteristics

 $V_{CC} = 5 V, T_A = 25^{\circ}C$

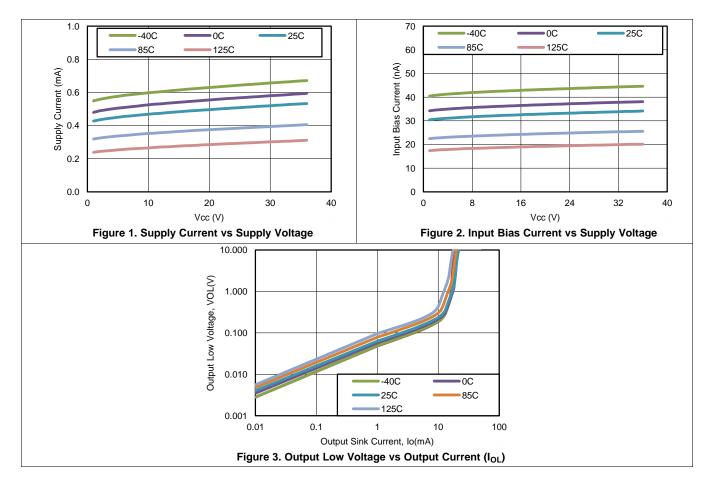
PARAMETER	TEST CONDITIONS			UNIT
Description	D composited to $\Gamma(1)$ (2)	100-mV input step with 5-mV overdrive	1.3	
Response time	R_L connected to 5 V through 5.1 k Ω , C_L = 15 pF ⁽¹⁾ (2)	TTL-level input step	0.3	μs

(1) C_{L} includes probe and jig capacitance.

(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



7.7 Typical Characteristics





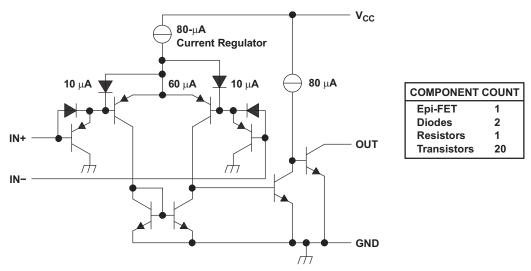
8 Detailed Description

8.1 Overview

The TL331 is a single comparator with the ability to operate up to 36 V on the supply pin. This standard device has proven ubiquity and versatility across a wide range of applications. This is due to it's very wide supply voltages range (2 V to 36 V), low Iq and fast response.

The open-drain output allows the user to configure the output's logic low voltage (V_{OL}) and can be utilized to enable the comparator to be used in AND functionality.

8.2 Functional Block Diagram



Current values shown are nominal.

8.3 Feature Description

TL331 consists of a PNP darlington pair input, allowing the device to operate with very high gain and fast response with minimal input bias current. The input Darlington pair creates a limit on the input common mode voltage capability, allowing TL331 to accurately function from ground to $V_{CC} - 1.5$ V differential input. This is enables much head room for modern day supplies of 3.3 V and 5.0 V.

The output consists of an open drain NPN (pull-down or low side) transistor. The output NPN will sink current when the positive input voltage is higher than the negative input voltage and the offset voltage. The VOL is resistive and will scale with the output current. Please see Figure 3 for V_{OL} values with respect to the output current.

8.4 Device Functional Modes

8.4.1 Voltage Comparison

The TL331 operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputting a logic low or high impedance (logic high with pull-up) based on the input differential polarity.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

TL331 will typically be used to compare a single signal to a reference or two signals against each other. Many users take advantage of the open drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes TL331 optimal for level shifting to a higher or lower voltage.

9.2 Typical Application

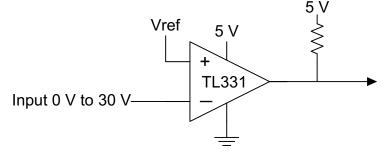


Figure 4. Typical Application Schematic

9.2.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

Table 1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input Voltage Range	0 V to V_{CC} – 1.5 V
Supply Voltage	2 V to 36 V
Logic Supply Voltage (R _{PULLUP} Voltage)	2 V to 36 V
Output Current (V _{LOGIC} /R _{PULLUP})	1 µA to 20 mA
Input Overdrive Voltage	100 mV
Reference Voltage	2.5 V
Load Capacitance (CL)	15 pF

9.2.2 Detailed Design Procedure

When using TL331 in a general comparator application, determine the following:

- Input voltage range
- Minimum overdrive voltage
- Output and drive current
- Response time



9.2.2.1 Input Voltage Range

When choosing the input voltage range, the input common mode voltage range (V_{ICR}) must be taken in to account. If temperature operation is above or below 25°C the V_{ICR} can range from 0 V to V_{CC} – 1.5 V. This limits the input voltage range to as high as V_{CC} – 1.5 V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.

Below is a list of input voltage situation and their outcomes:

- 1. When both IN- and IN+ are both within the common mode range:
 - (a) If IN- is higher than IN+ and the offset voltage, the output is low and the output transistor is sinking current
 - (b) If IN- is lower than IN+ and the offset voltage, the output is high impedance and the output transistor is not conducting
- 2. When IN- is higher than common mode and IN+ is within common mode, the output is low and the output transistor is sinking current
- 3. When IN+ is higher than common mode and IN- is within common mode, the output is high impedance and the output transistor is not conducting
- 4. When IN- and IN+ are both higher than common mode, the output is low and the output transistor is sinking current

9.2.2.2 Minimum Overdrive Voltage

Overdrive Voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage (V_{IO}). In order to make an accurate comparison the Overdrive Voltage (V_{OD}) should be higher than the input offset voltage (V_{IO}). Overdrive voltage can also determine the response time of the comparator, with the response time decreasing with increasing overdrive. Figure 5 and Figure 6 show positive and negative response times with respect to overdrive voltage.

9.2.2.3 Output and Drive Current

Output current is determined by the load/pull-up resistance and logic/pull-up voltage. The output current will produce a output low voltage (V_{OL}) from the comparator. In which V_{OL} is proportional to the output current. Use Figure 3 to determine V_{OL} based on the output current.

The output current can also effect the transient response. More will be explained in the next section.

9.2.2.4 Response Time

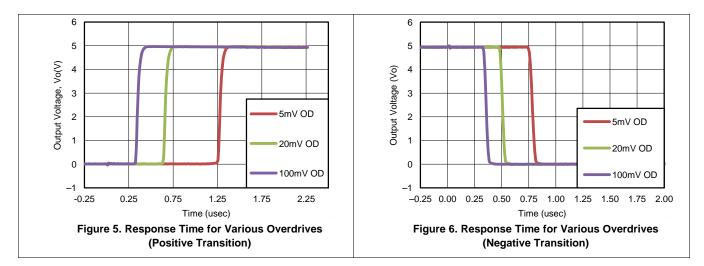
The transient response can be determined by the load capacitance (C_L), load/pull-up resistance (R_{PULLUP}) and equivalent collector-emitter resistance (R_{CE}).

- The positive response time (τ_p) is approximately τ_P ~ R_{PULLUP} × C_L
- The negative response time (T_N) is approximately $T_N \sim R_{CE} \times C_L$
 - R_{CE} can be determine by taking the slope of Figure 3 in it's linear region at the desired temperature, or by dividing the V_{OL} by I_{out}

TL331 SLVS238G – AUGUST 1999 – REVISED JANUARY 2015

9.2.3 Application Curves

The following curves were generated with 5 V on V_{CC} and V_{Logic}, $R_{PULLUP} = 5.1 \text{ k}\Omega$, and 50 pF scope probe.



10 Power Supply Recommendations

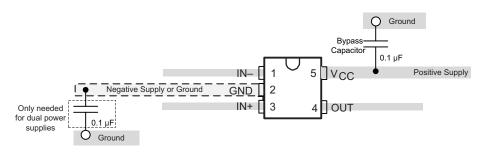
For fast response and comparison applications with noisy or AC inputs, it is recommended to use a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can eat into the comparator's input common mode range and create an inaccurate comparison.

11 Layout

11.1 Layout Guidelines

For accurate comparator applications without hysteresis it is important maintain a stable power supply with minimized noise and glitches, which can affect the high level input common mode voltage range. In order to achieve this, it is best to add a bypass capacitor between the supply voltage and ground. This should be implemented on the positive power supply and negative supply (if available). If a negative supply is not being used, do not put a capacitor between the IC's GND pin and system ground.

11.2 Layout Example







12 Device and Documentation Support

12.1 Trademarks

All trademarks are the property of their respective owners.

12.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.3 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



22-Nov-2019

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL331IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(T1IG, T1IL, T1IS)	Samples
TL331IDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	T1IG	Samples
TL331IDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	T1IG	Samples
TL331IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(T1IG, T1IL, T1IU)	Samples
TL331IDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	T1IG	Samples
TL331KDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 105	(T1KG, T1KL)	Samples
TL331KDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	(T1KG, T1KL)	Samples
TL331KDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 105	(T1KG, T1KL)	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

22-Nov-2019

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TL331 :

• Automotive: TL331-Q1

• Enhanced Product: TL331-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL331IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TL331IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TL331IDBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TL331IDBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TL331IDBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TL331KDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

Texas Instruments

www.ti.com

PACKAGE MATERIALS INFORMATION

25-Sep-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL331IDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TL331IDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TL331IDBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
TL331IDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TL331IDBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
TL331KDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0

DBV0005A



PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. Refernce JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.



DBV0005A

EXAMPLE BOARD LAYOUT

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DBV0005A

EXAMPLE STENCIL DESIGN

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2019, Texas Instruments Incorporated